# **Axial Lead Rectifier**

... employing the Schottky Barrier principle in a large area metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlap contact. Ideally suited for use as rectifiers in low-voltage, high-frequency inverters, free wheeling diodes, and polarity protection diodes.

- Extremely Low V<sub>f</sub>
- Low Power Loss/High Efficiency
- Highly Stable Oxide Passivated Junction
- Low Stored Charge, Majority Carrier Conduction
- **Mechanical Characteristics:**
- Case: Epoxy, Molded
- Weight: 0.4 gram (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 220°C Max. for 10 Seconds, 1/16" from case
- Shipped in plastic bags, 1000 per bag
- Available Tape and Reeled, 5000 per reel, by adding a "RL" suffix to the part number
- Polarity: Cathode indicated by Polarity Band
- ESD Ratings: Machine Model = AHuman Body Model = 2
- Marking: MBR3060

### **MAXIMUM RATINGS**

• Case: Epoxy, Molded						
• Weight: 0.4 gram (approximately	,					
• Finish: All External Surfaces Con	rosion Res	istant and Ter	minal	l li.		
Leads are Readily Solderable					~~ .O	$\square$
• Lead and Mounting Surface Tem	•					·
220°C Max. for 10 Seconds, 1/16		e				
• Shipped in plastic bags, 1000 per	-			SIN		
• Available Tape and Reeled, 5000	per reel, by	y adding a "R	L" suffi	sto schille		
the part number			6			
• Polarity: Cathode indicated by Po		ł		0, 6,		
• ESD Ratings: Machine Mode		0	$\langle \cdot \rangle$		AXIAL LEA	٩D
Human Body N	4 odel = 2			` <u>,</u> O`	CASE 59-	
Marking: MBR3060		E.	10		PLASTIC	;
		O' A				
MAXIMUM RATINGS	C.C.	b G		Ň	ARKING DIA	GR
Rating	Symbol	Max	Unit			
Peak Repetitive Reverse Voltage	V <sub>BRM</sub>	60	V	ح	MBR306	٥F
Working Peak Reverse Voltage	V <sub>RWM</sub>					
DC Blocking Voltage	Vr	19		Μ	IBR3060 = Devi	ce C
Average Rectified Forward Current	lo	3.0	А			
$T_L = 125^{\circ}C (R_{\theta JL} = 13^{\circ}C/W,$ P.C. Board Mounting)	2.8					
6,		105	•			
Non-Repetitive Peak Surge Current	IFSM	125	A	ORE	DERING INFO	RM
Operating and Storage Junction	T <sub>J</sub> , T <sub>stq</sub>	-65 to +150	°C	Device	Package	
Temperature Range	IJ, Istg	-05 10 +150	U		Avial Laad	
(Reverse Voltage Applied)				MBR3060	Axial Lead	
Peak Operating Junction	T <sub>J(pk)</sub>	150	°C	MBR3060RL	Axial Lead	50
Temperature	- (()					
Temperature (Forward Current Applied)	- ()					



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SCHOTTKY BARRIER RECTIFIER 3.0 AMPERES 60 VOLTS

### **MARKING DIAGRAM**



MBR3060 = Device Code

#### **ORDERING INFORMATION**

Device	Package	Shipping
MBR3060	Axial Lead	1000 Units/Bag
MBR3060RL	Axial Lead	5000/Tape & Reel

#### THERMAL CHARACTERISTICS

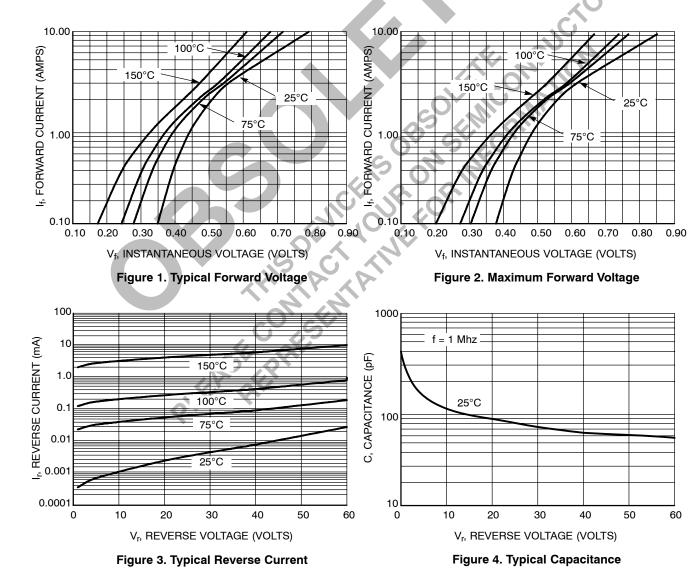
Characteristic		Max	Unit
Thermal Resistance, Junction-to-Lead (Note 1, see Note 3, Mounting Method 3)	$R_{\theta JL}$	13	°C/W
Thermal Resistance, Junction-to-Ambient (see Note 3, Mounting Method 3)	$R_{\thetaJA}$	50	°C/W

#### ELECTRICAL CHARACTERISTICS (T<sub>L</sub> = 25°C unless otherwise noted) (Note 1)

Characteristic			Max	Unit
Maximum Instantaneous Forward Voltage (Note 2) ( $I_f = 3.0 \text{ Amp}$ ), $T_L = 25^{\circ}\text{C}$ ( $I_f = 3.0 \text{ Amp}$ ), $T_L = 100^{\circ}\text{C}$		V <sub>f</sub>	0.62 0.59	V
Maximum Instantaneous Reverse Current (Note 2) ( $V_r = 60 V$ ), $T_L = 25^{\circ}C$ ( $V_r = 60 V$ ), $T_L = 100^{\circ}C$		I <sub>r</sub>	150 10	μA mA

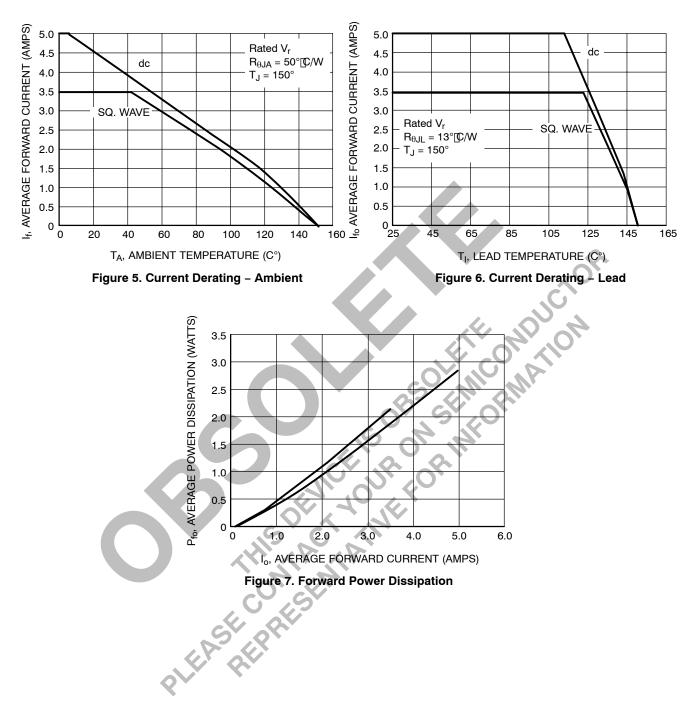
1. Lead Temperature reference is cathode lead at printed wiring board.

2. Pulse Test: Pulse Width = 300  $\mu$ s, Duty Cycle = 2.0%.



## TYPICAL CHARACTERISTICS

## **TYPICAL CHARACTERISTICS**



## NOTE 3 — MOUNTING DATA

Data shown for thermal resistance junction–to–ambient ( $R_{\theta JA}$ ) and thermal resistance junction–to–lead ( $R_{\theta JL}$ ) for the mountings shown is to be used as typical guideline values for preliminary engineering, or in case the tie point temperature cannot be measured.



Mounting	Le				
Method	1/8	1/4	1/2	3/4	$\mathbf{R}_{\theta \mathbf{JA}}$
1	52	65	72	85	°C/W
2	67	80	87	100	°C/W
3	50			°C/W	

TYPICAL VALUES FOR  $\textbf{R}_{\theta \textbf{JL}}$  IN STILL AIR

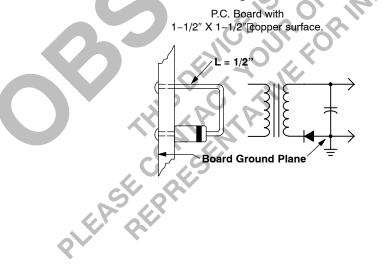
Mounting	Lead			
Method	1/8	1/4	1/2	$\mathbf{R}_{\theta \mathbf{JA}}$
1	15	23	37	°C/W
2	30	38	52	°C/W
3	•	13		°C/W

**Mounting Method 1** 

P.C. Board with 1-1/2" X 1-1/2" copper surface.

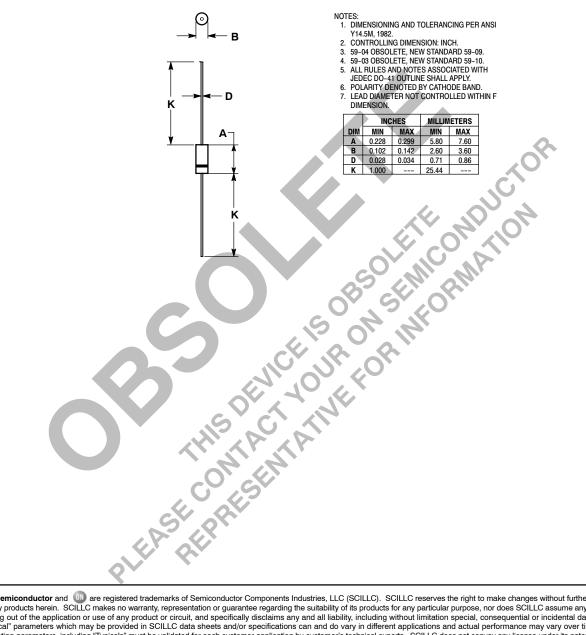
**Mounting Method** Vector Push-In Terminals T-28

Mounting Method 3



#### PACKAGE DIMENSIONS

AXIAL LEAD CASE 59–09 ISSUE R



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